

Pin Assignment

Pin #	Description	Pin #	Description
1	A	15	A
2	F2	16	F15
3	C	17	C
4	F4	18	F13
5	F6	19	F11
6	C	20	C
7	F8	21	F9
8	F10	22	F7
9	C	23	C
10	F12	24	F5
11	F14	25	F3
12	C	26	C
13	F16	27	F1
14	A	28	A

A = Common Anode

C = Common Cathode

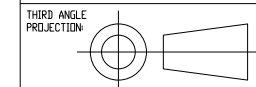
F_n = SiPM n Fast output

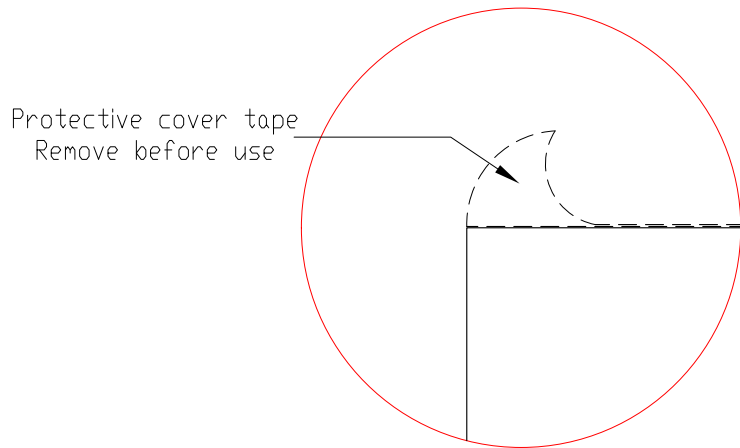
DATE: 05 Feb 2018 | DWG. NO: SND0200 | REVISION B

TITLE:
ArrayRA-0116A20-DFN

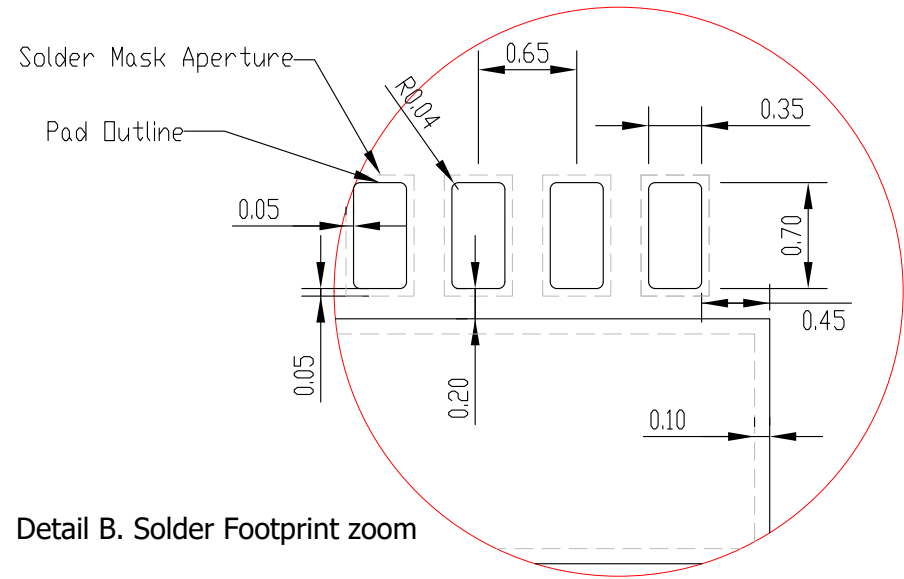
ALL DIMENSIONS ARE IN mm
GENERAL TOLERANCE (UNLESS SPECIFIED) ±0.1mm
DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE | DO NOT SCALE

SensL Technologies Ltd | Sheet 1 of 2
www.sensl.com

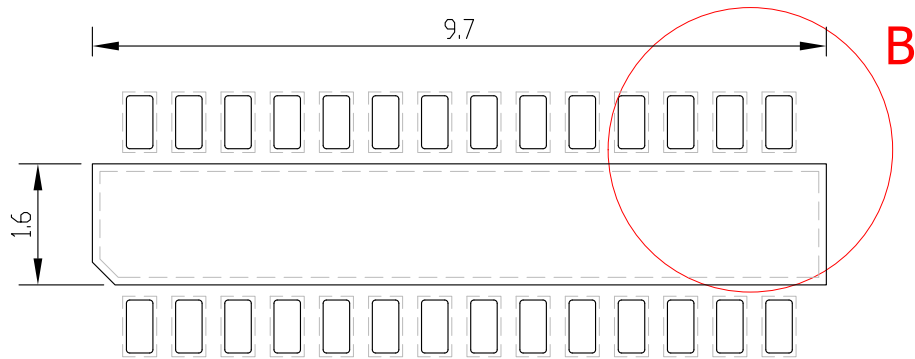




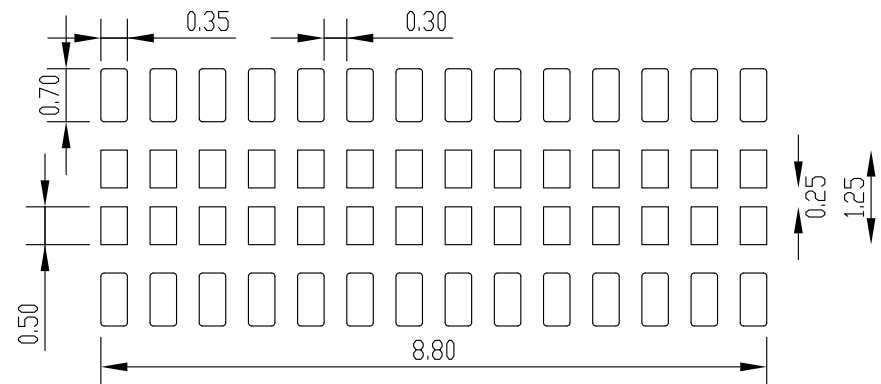
Detail A. Cover Tape
Not to Scale



Detail B. Solder Footprint zoom



Example Solder Footprint



Example Solder Stencil Design

NOTE

The Exposed pad (EPAD) may be soldered to the PCB or left unsoldered. If soldering the EPAD it may be electrically floating or connected to the Anode. If the EPAD is left unsoldered ensure that the PCB area under the EPAD does not contain exposed electrical contacts, such as vias, to avoid shorting between EPAD and other traces.

Footprint is provided for information purposes only. Consult with PCB and assembly supplier for optimal footprint and stencil design and soldering guidance based on their equipment and capabilities.

DATE: 05 Feb 2018	DWG. NO: SND0200	REVISION B
TITLE: ArrayRA-0116A20-DFN		
ALL DIMENSIONS ARE IN mm		
GENERAL TOLERANCE (UNLESS SPECIFIED) ±0.1mm		
DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE		DO NOT SCALE
SensL Technologies Ltd www.sensl.com		Sheet 2 of 2
THIRD ANGLE PROJECTION:		